- Single-Chip Interface Solution for AppleTalk™ and LocalTalk™
- Designed to Operate Up To 1 Mbps In AppleTalk and LocalTalk
- Switched-Capacitor Voltage Converter Allows for Single 5-V Operation
- 4-kV ESD Protection on Bus Terminals
- Combines Multiple Components into a Single Chip Solution
- LinBiCMOS™ Process Technology

description

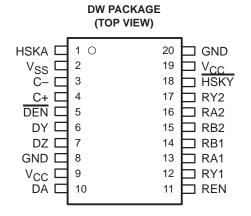
The SN75LBC775 is a low-power LinBiCMOS™ device that incorporates the drivers and receivers for an AppleTalk or a LocalTalk interface and a switched-capacitor voltage converter for a single 5-V supply operation. LocalTalk uses a hybrid of RS-422 with the transceiver connected to the network through a small isolation transformer. The AppleTalk mode provides point-to-point communications and uses the same differential driver and receiver as LocalTalk with the addition of a hybrid RS-423, single-ended handshake driver (HSK) and receiver. In the AppleTalk mode, the port connects directly to the receiver with no isolation transformer.

While the device power is turned off ($V_{CC} = 0$) or disabled in the LocalTalk mode, the outputs are in a <u>high</u>-impedance state. When the driver enable (\overline{DEN}) terminal is high, both the differential and serial driver outputs are in a high-impedance state.

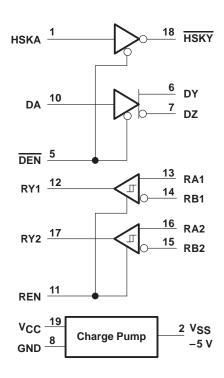
The receiver output can be disabled and becomes a high impedance when the REN terminal is low.

A switched-capacitor voltage converter generates the negative voltage required from a single 5-V supply using two 22- μ F capacitors. One capacitor is between the C+ and C- terminals and the second is between VSS and ground.

The SN75LBC775 is characterized for operating over the temperature range of 0°C to 70°C.



functional diagram





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LocalTalk and AppleTalk are trademarks of Apple Computer, Inc. LinBiCMOS is a trademark of Texas Instruments Incorporated.



DRIVER FUNCTION TABLE

INF	PUT	ENABLE		OUTP	JT						
DA	HSKA	DEN	Α	В	HSKY						
Н	Х	L	Н	L	Х						
L	Х	L	L	Н	Х						
X	Н	L	Х	Χ	L						
X	L	L	Х	Χ	Н						
OPEN	OPEN	L	Н	L	L						
X	X	Н	z	Z	Z						
Χ	Х	OPEN	Z	Z	z						

RECEIVER FUNCTION TABLE

	IN	PUT	ENABLE	OUTPUT		
	RA RB		REN	RY		
Γ	H L		Н	Н		
ı	L	Н	Н	L		
ı	OPI	EN	Н	Н		
	SHORT [†]		Н	?		
L	Х	(L	Z		

$$t-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$$

H = high level,

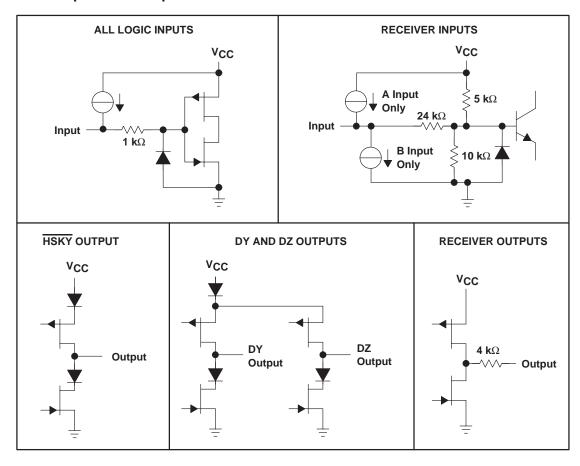
L = low level,

X = irrelevant,

? = indeterminate,

Z = high impedance (off)

schematics of inputs and outputs



SN75LBC775 SINGLE-CHIP APPLETALK™ AND LOCALTALK™ TRANSCEIVER

SLLS216A - MAY 1995 - REVISED JANUARY 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†
Supply voltage range, V _{CC} (see Note 1)
Supply voltage range, V _{SS}
Receiver input voltage range, V _I (RA)
Receiver differential input voltage range, V _{ID} –12 V to 12 V
Receiver output voltage range, V _O (RY)
Driver output voltage range, VO (Power Off) (DY, DZ, HSKY)15 V to 15 V
(Power On) (DY, DZ, HSKY) –11 V to 11 V
Driver input voltage range, V _I (DA, HSKA, DEN, REN)
Electrostatic discharge (see Note 2) Class 3, A: Bus terminals
All other terminals
Continuous total power dissipation
Operating free-air temperature range, T _A

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. This maximum rating is tested according to MIL-STD-883C, Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 85°C POWER RATING
DW	1125 mW	9.0 mW/°C	585 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, VIH	DA, HSKA, DEN, REN	2			V
Low-level input voltage, V _{IL}	DA, HSKA, DEN, REN			0.8	V
Receiver input common-mode voltage ran	-7		7	V	
Differential input voltage, V _{ID} ‡		-12		12	V
Voltage-converter filter capacitance		22			μF
Voltage-converter filter-capacitor equivalent	e-converter filter capacitance e-converter filter-capacitor equivalent series resistance (ESR)			2	Ω
Operating free-air temperature, TA		0		70	°C

[‡] The algebraic convention, in which the less-positive (more negative) limit is designated minimum, is used in this data sheet.

NOTES: 1. All voltage values are with respect to network ground terminal unless otherwise noted.

DRIVER

electrical characteristics over recommend operating characteristics (unless otherwise noted)

	PARAMETE	R	TEST CO	NDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	Single ended	$R_1 = 3 k\Omega$	See Figure 1	3.7			V
VOL	Low-level output voltage	Sirigle erided	K_ = 3 Ks2,	See Figure 1			-3.7	V
V _{OD}	Magnitude of differential out	See Figure 2		4.0	5.6		V	
Δ V _{OD}	Change in differential voltage	See Figure 2			10	250	mV	
Voc	Common-mode output volta	See Figure 3		-1		3	V	
ΔVOC(SS)	Change in steady-state com	mon-mode output voltage	See Figure 3				±200	mV
loz	High-impedance output curr	ent	$V_{CC} = 0, -10 \text{ V}$	′ ≤ V _O ≤ 10 V			±100	μΑ
los	Short-circuit output current		$-5 \text{ V} \leq \text{V}_{\text{O}} \leq 5 \text{ V}$	V			450	mA
Icc	Supply current		DEN at 0 V, No load	REN at 5 V,		5	10	mA
lН	High-level input current		V _I = 5 V				200	μΑ
1	All terminals except REN		1/: 0			-100	-200	μΑ
¹IL	low-level input current	REN	V _I = 0			-300	-455	μΑ

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommend operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
	Propagation delay time, high- to low-level	Single ended			155	300	ns
tPHL	Propagation delay time, high- to low-level	Differential	1 1		115	180	ns
	Propagation delay time law to high layel	Single ended			140	300	ns
tPLH	Propagation delay time, low- to high-level	Differential			115	180	ns
tpZL	Propagation delay time, high-impedance to lov			100	250	ns	
^t PZH	Propagation delay time, high-impedance to high	See Figures 1 and 2		100	250	ns	
tPLZ	Propagation delay time, low-level to high-impe			100	250	ns	
tPHZ	Propagation delay time, high-level to high-imp	edance output	See Figures 1 and 2		100	250	ns
	Rise time	Single ended			135	300	ns
t _r	Rise time	Differential	1 1		90	180	ns
4.	Fall time	Single ended]		145	300	ns
tf	Fall time	Differential]		95	180	ns
t	Pulso skow Itania tana I	Single ended] i		15	50	ns
^t sk(p)	Pulse skew, tpLH-tpHL	Differential	1		2	22	ns

[‡] The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet.

RECEIVER

electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going differential input voltage threshold				200	mV
V _{IT} _	Negative-going differential input voltage threshold [‡]]	-200			mV
V _{hys}	Input voltage hysteresis (VIT+ - VIT-)	$I_{OH} = 2 \text{ mA},$ $I_{OL} = -2 \text{mA},$ See Figure 4		30		mV
Vон	High-level output voltage	Coo rigulo 4	2	4.5		V
VOL	Low-level output voltage				0.8	V
las	Object admits a standard assessed t	V _O = 0	8	50	85	mA
los	Short-circuit output current‡	VO = VCC	-85	-50	-8	mA
rį	Input resistance	$V_{CC} = 0 \text{ or } 5.25 \text{ V}, -12 \text{ V} \le V_{I} \le 12 \text{ V}$	6			kΩ

switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CON	MIN	TYP†	MAX	UNIT	
tPHL	Propagation delay time, high- to low-level output				25	60	ns
tPLH	Propagation delay time, low- to high-level output		0.45.5		22	60	ns
t _r	Rise time	$R_L = 2 k\Omega$, See Figure 4	$C_L = 15 pF$,		8	25	ns
t _f	Fall time]	I		7	25	ns
tSK(P)	Pulse skew, tpLH - tpHL				3	20	ns
t _{PZL}	Receiver output enable time to low-level output				50		ns
tPZH	Receiver output enable time to high-level output	C 90 pF	See Figure 5		50		ns
t _{PLZ}	Receiver output disable time to low-level output	C _L = 80 pF, See Fig	See Figure 5		50		ns
tPHZ	Receiver output disable time to high-level output		ľ		50		ns

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 5 V and T_A = 25°C.

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C. ‡ The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet.

PARAMETER MEASUREMENT INFORMATION

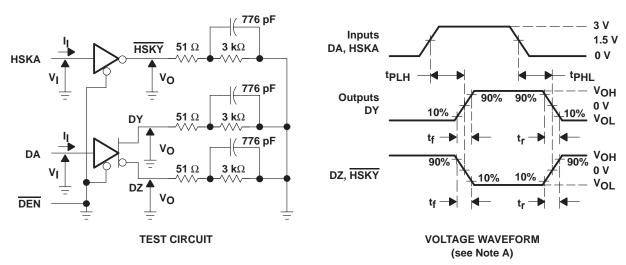
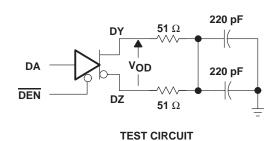
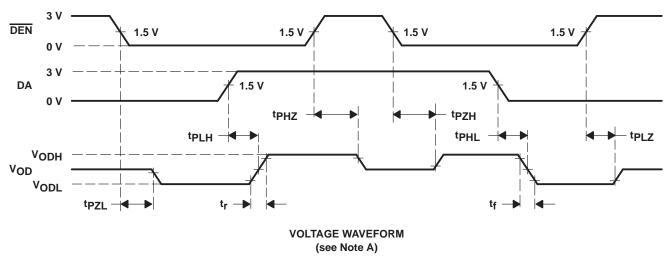


Figure 1. Driver Propagation and Transition Times for AppleTalk





NOTE A: The input waveform t_f , $t_f < = 10$ ns

Figure 2. Driver Propagation and Transition Times for LocalTalk



PARAMETER MEASUREMENT INFORMATION

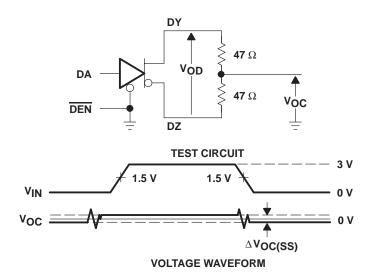
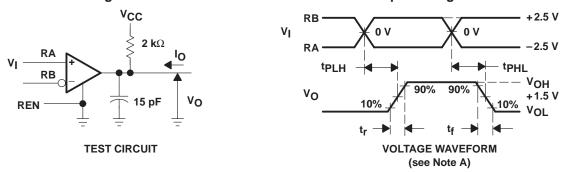


Figure 3. Differential Driver Common Mode Output Voltage Tests



NOTE A: The input waveform t_f , $t_f < = 10$ ns

Figure 4. Receiver Propagation and Transition Times

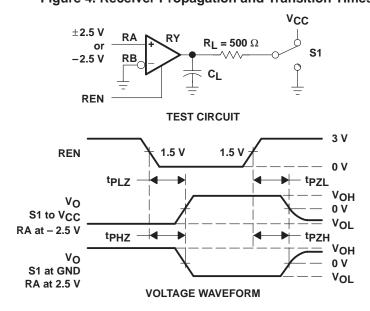


Figure 5. Receiver Enable and Disable Test Circuit and Waveform



TYPICAL CHARACTERISTICS

MAXIMUM DRIVER DATA RATE vs

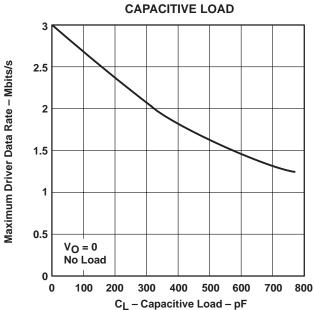
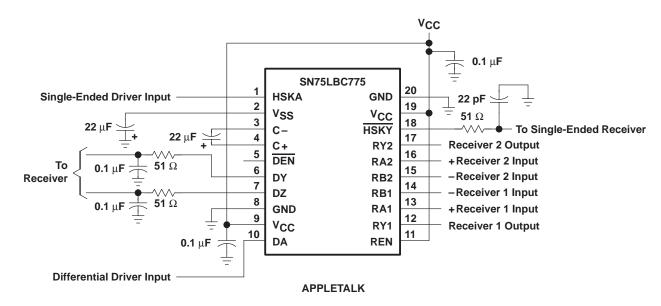
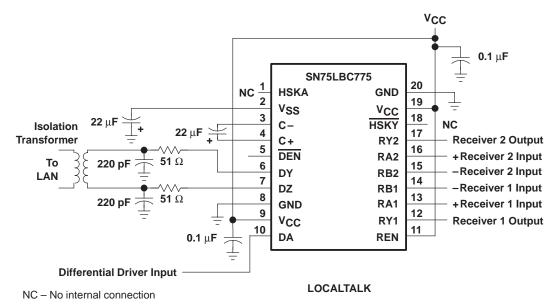


Figure 6

APPLICATION INFORMATION





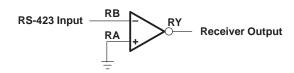


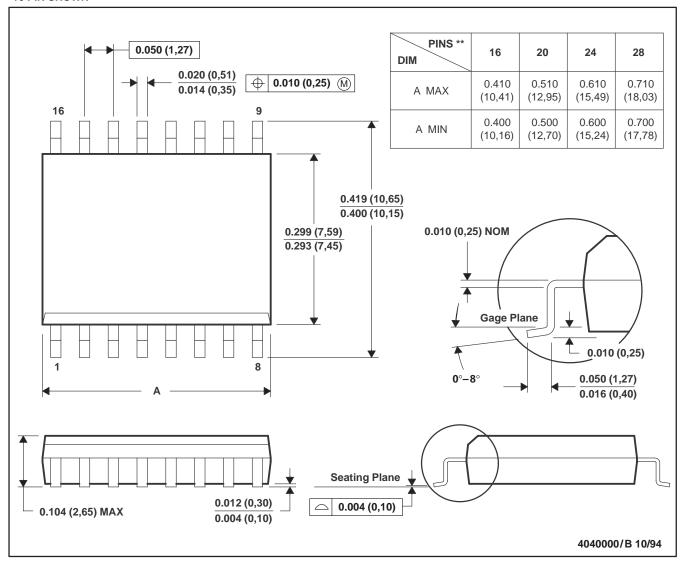
Figure 7. Receiving RS-423 Signals With a Differential Receiver

MECHANICAL INFORMATION

DW (R-PDSO-G**)

16 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: B. All linear dimensions are in inches (millimeters).

C. This drawing is subject to change without notice.

D. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

E. Falls within JEDEC MS-013





.com 2-Oct-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75LBC775DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC775DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC775DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC775DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

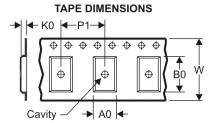
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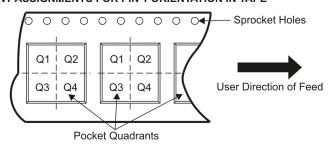
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

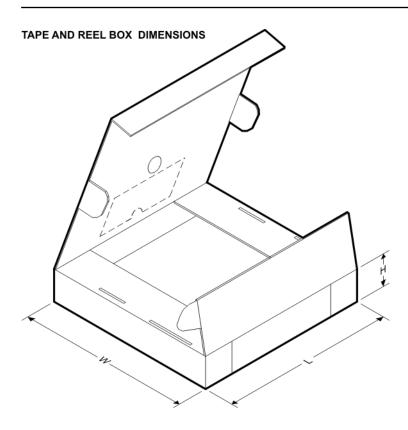
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75LBC775DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.1	2.65	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LBC775DWR	SOIC	DW	20	2000	346.0	346.0	41.0

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